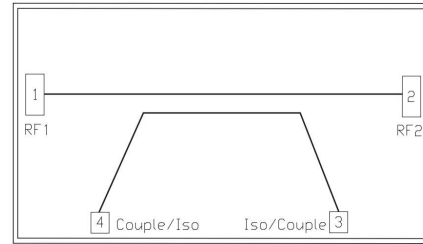


### Performance

- Frequency: 6~18GHz
- Coupling: 15dB
- Coupling Flatness: 3.5dB
- Chip size: 1.84\*1.3\*0.1mm

### Function Diagram

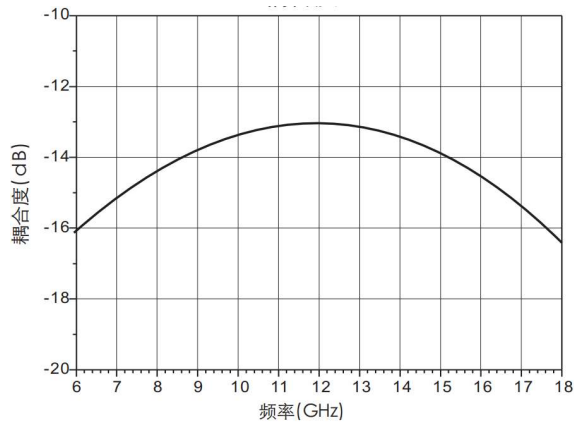


### Electrical Specifications (Ta=+25°C, 50Ω system)

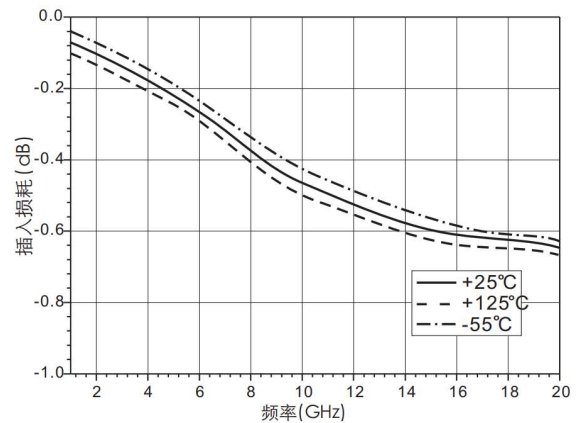
| Parameter                   | Min  | Typical | Max  | Unit |
|-----------------------------|------|---------|------|------|
| Frequency Range             | 6~18 |         |      | GHz  |
| Coupling                    | 13   | 15      | 16.4 |      |
| Insertion Loss              | 0.3  | 0.5     | 0.7  | dB   |
| Input Return loss           | 15   | 20      | -    | dB   |
| Thru Output Return loss     | 25   | 30      | -    | dB   |
| Coupling Output Return loss | 17   | 20      | -    | dB   |

### Test Curves (Die chip + Bonding line test)

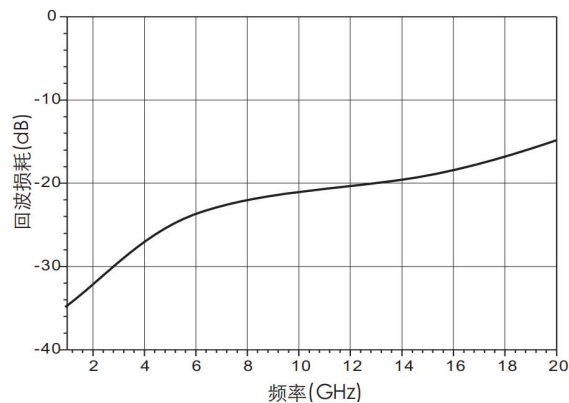
Coupling vs. Freq



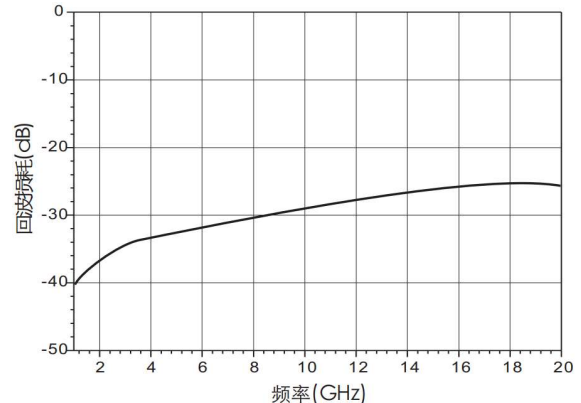
Insertion loss vs. Freq

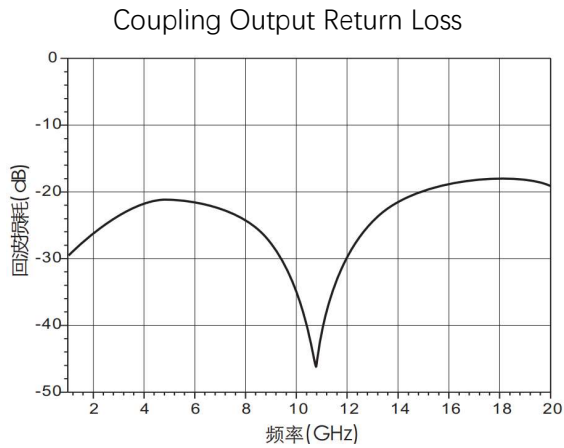


Input Return Loss vs. Freq



Thru output Return loss vs. Freq





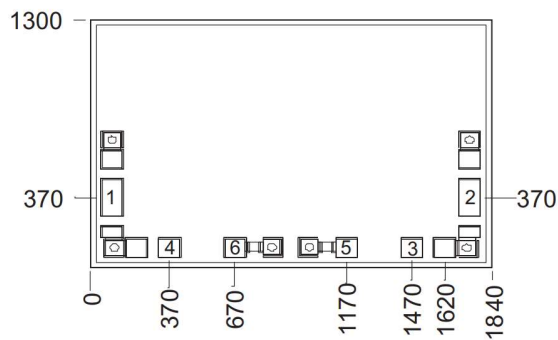
### Absolute Rating

|                         |            |
|-------------------------|------------|
| Storage Temperature     | -65~+150°C |
| Operating Temperature   | -55~+125°C |
| Max Input Power         | 5W         |
| Static Protection (HBM) | Class 1A   |



ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS

### Outline Size



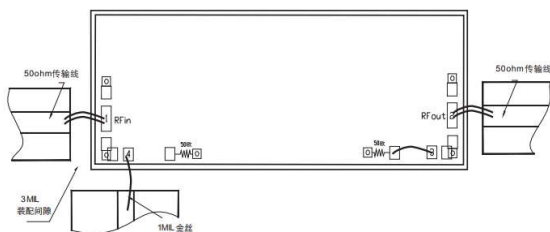
### Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, Pad size: 200\*100(um), 100\*100(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um

### Bonding Pads Definition

| Number | Symbol     | Description   |
|--------|------------|---|
| 1      | RFin       | RF input port, 50ohm  |
| 2      | RFout      | RF output port, 50 ohm  |
| 3,4    | Couple/ISO | Choose either one as couple output port, another port connect to 50Ω resistor pad |
| 5,6    | LOAD       | 50ohm resistor pads   |

### Application (Chip left side couple output)



### Application (Chip right side couple output)

